



ACM Research Unveils Ultra ECDP Electrochemical Deplating Tool for Compound Semiconductor Gold Etch Processes

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The Ultra ECDP System Delivers Superior Uniformity and Minimized Undercut for High-Precision Au Bump, Thin Film, and Deep-Hole Deplating

FREMONT, Calif., Sept. 17, 2025 (GLOBE NEWSWIRE) -- [ACM Research, Inc.](#) ("ACM") (NASDAQ: ACMR), a leading supplier of wafer and panel processing solutions for semiconductor and advanced packaging applications, today announced the launch of its first Ultra ECDP Electrochemical Deplating ("Ultra ECDP") tool specifically designed for wide bandgap compound semiconductor manufacturing. The Ultra ECDP tool is engineered for electrochemical wafer-level gold (Au) etching performed outside of the wafer pattern area and delivers improved uniformity, smaller undercut and enhanced gold line appearance.

The Ultra ECDP tool offers specialized processes including Au bump removal, thin film Au etching, and deep-hole Au deplating, supported by integrated pre-wet and cleaning chambers. It features precise chemistry circulation and advanced multi-anode electrochemical deplating technology, the system achieves minimized side etching, excellent surface finish, and superior uniformity across all features.

"The compound semiconductor market continues to grow with strong demand from electric vehicles, 5G/6G communication, RF and AI applications, among others," said Dr. David Wang, President and Chief Executive Officer of ACM Research. "Gold is emerging as an advantageous material for these devices, delivering high conductivity, corrosion resistance, and malleability, but it also presents etching and plating challenges. We believe ACM's Ultra ECDP tool overcomes these barriers to provide a reliable, production-ready solution that helps customers achieve high-performance results. It is another example of how we innovate to address our customers' challenges."

The Ultra ECDP tool is engineered to address the evolving requirements of compound semiconductor manufacturing, accommodating the distinct physical characteristics—such as weight, stress, and thickness—of diverse substrates, including silicon carbide (SiC), gallium arsenide (GaAs), lithium phosphate (Li₃PO₄) and etc. Featuring a modular design, the Ultra ECDP tool has the flexibility to integrate both plating and deplating processes within a single platform, and utilizes multi-anode technology for controlling deplating in different areas. The Ultra ECDP tool also offers horizontal full-face deplating to prevent cross contamination during processing.

About the Ultra ECDP Tool

The Ultra ECDP tool is compatible with 6-inch and 8-inch platforms and accommodates 150 millimeter (mm), 159mm and 200mm wafer sizes. The system is configurable with two open cassettes and one vacuum arm, providing adaptability for various manufacturing environments.

Forward-Looking Statements

Certain statements contained in this press release are not historical facts and may be forward-looking statements within the meaning of the Private Securities Litigation Reform Act of 1995. Words such as "plans," "expects," "believes," "anticipates," "designed," and similar words are intended to identify forward-looking statements. Forward-looking statements are based on ACM management's current expectations and beliefs and involve a number of risks and uncertainties that are difficult to predict and that could cause actual results to differ materially from those stated or implied by the forward-looking statements. A description of certain of these risks, uncertainties and other matters can be found in filings ACM makes with the U.S. Securities and Exchange Commission, all of which are available at www.sec.gov. Because forward-looking statements involve risks and uncertainties, actual results and events may differ materially from results and events currently expected by ACM. Readers are cautioned not to place undue reliance on these forward-looking statements, which speak only as of the date hereof. ACM undertakes no obligation to publicly update these forward-looking statements to reflect events or circumstances that occur after the date hereof or to reflect any change in its expectations with regard to these forward-looking statements or the occurrence of unanticipated events.

About ACM Research, Inc.

ACM develops, manufactures and sells semiconductor process equipment spanning cleaning, electroplating, stress-free polishing, vertical furnace processes, track, PECVD, and wafer- and panel-level packaging tools, enabling advanced and semi-critical semiconductor device manufacturing. ACM is committed to delivering customized, high-performance, cost-effective process solutions that semiconductor manufacturers can use in numerous manufacturing steps to improve productivity and product yield.

For more information, visit <https://www.acmr.com/>.

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